NEW!
Two Section
Models

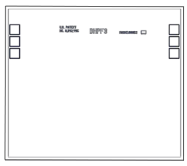
MMIC

REFLECTIONLESS FILTERS DICE

50Ω DC to 26 GHz

The Big Deal

- *High Stopband rejection, up to 41 dB*
- *Patented design terminates stopband signals*
- *Pass band cut off up to 11 GHz*
- *Pass band up to 26 GHz*
- *Excellent repeatability through IPD* process*



Product Overview

Mini-Circuits' ***X-Series*** of reflectionless filters now includes two-section models, giving you ultra-high rejection in the stopband – up to 41 dB! Reflectionless filters employ a patented filter topology which absorbs and terminates stopband signals internally rather than reflecting them back to the source. This new capability enables unique applications for filter circuits beyond those suited to traditional approaches. Traditional filters are reflective in the stopband, sending signals back to the source at 100% power. These reflections interact with neighboring components and often result in intermodulation and other interferences. By eliminating stopband reflections, reflectionless filters can readily be paired with sensitive devices and used in applications that otherwise require circuits such as isolation amplifiers or attenuators.

Key Features	Advantages
Easy integration with sensitive reflective components, e.g. mixers, multipliers	Reflectionless filters absorb unwanted signals, preventing reflections back to the source. This reduces generation of additional unwanted signals without the need for extra components like attenuators, improving system dynamic range and saving board space.
High stopband rejection, up to 41 dB	Ideal for applications where suppression of strong spurious signals and intermodulation products is needed.
Enables stable integration of wideband amplifiers	Because reflectionless filters maintain good impedance in the stopband; they can be integrated with high gain, wideband amplifiers without the risk of creating instabilities in these out of band regions.
Cascadable	Reflectionless filters can be cascaded in multiple sections to provide sharper and higher attenuation, while also preventing any standing waves that could affect passband signals. Low & highpass filters can be cascaded to realize bandpass filters.
Excellent power handling in a tiny surface mount device up to 1W in passband	High power handling extends the usability of these filters to the transmit path for inter-stage filtering.
Excellent repeatability of RF performance	Through semiconductor IPD process, X-series filters are inherently repeatable for large volume production.
Excellent stability over temperature	With ±0.3 dB variation over temperature ideal for use in wide temperature range applications without the need for additional temperature compensation.
Operating temperature up to 105˚C	Suitable for operation close to high power components.
Unpackaged die	Enables the user to integrate the filter directrly into hybrid.

*IPD – Integrated Passive Device, is a GaAs semiconductor process

Reflectionless

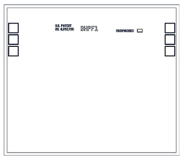
High Pass Filter Die

XHF-63M-D+

50Ω 5900 to 26000 MHz

Features

- Match to 50Ω in the stop band, eliminates undesired reflections
- Cascadable
- Excellent stopband rejection, 38 dB typ.
- Temperature stable, up to 105°C
- Protected by US Patents 8,392,495; 9,705,467, additional patent pending
- Protected by China Patent 201080014266.1
- Protected by Taiwan Patent I581494



+RoHS Compliant

The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

Ordering Information: Refer to Last Page

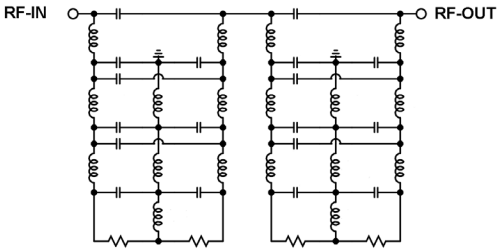
Applications

- Fixed satellite
- Mobile
- Space research

General Description

Mini-Circuits' XHF-63M-D+ three-section reflectionless filter Die employs a novel filter topology which absorbs and terminates stop band signals internally rather than reflecting them back to the source. This new capability enables unique applications for filter circuits beyond those suited to traditional approaches. Traditional filters are reflective in the stop band, sending signals back to the source at 100% of the power level. These reflections interact with neighboring components and often result in inter-modulation and other interferences. Reflectionless filters eliminate stop band reflections, allowing them to be paired with sensitive devices and used in applications that otherwise require circuits such as isolation amplifiers or attenuators.

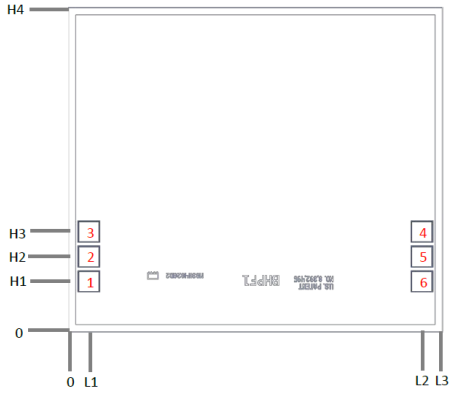
Simplified Schematic and Pad description



Pad#	Description
2	RF-IN
5	RF-OUT
1,3,4,6	Ground
Die bottom	Ground

Note: 1. Bond Pad material - Gold
2. Bottom of Die - Gold plated

Bonding Pad Position



Dimensions in µm, Typical

L1	L2	L3	H1	H2	H3	H4	Thickness	Bond pad size
80	1420	1500	200	300	400	1300	100	78 x 78

Electrical Specifications[1] at 25°C

Parameter		F#	Frequency (MHz)	Min.	Typ.	Max.	Unit
Stop Band	Rejection	DC - F'	DC - 3000		38		dB
		F' - F1	3000 - 4100		34		
	Frequency Cut-off	F2	5000		2.8		
	VSWR	DC - F'	DC - 3000		1.1		:1
		F' - F1	3000 - 4100		1.3		
Pass Band	Insertion Loss	F3 - F4	5900 - 10000		0.8		dB
		F4 - F5	10000 - 26000		0.9		
	VSWR	F3 - F4	5900 - 10000		1.2		:1
		F4 - F5	10000 - 26000		1.5		

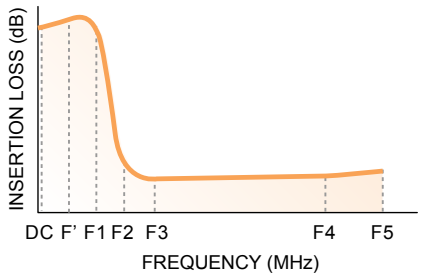
[1] Measured on die using MPI titan series 100µm pitch GSG probe.

Absolute Maximum Ratings[4]

Parameter	Ratings
Operating Temperature	-55°C to +105°C
RF Power Input, Passband (F3-F5)[2]	1W at 25°C
RF Power Input, Stopband (DC-F3)[3]	1.25W at 25°C

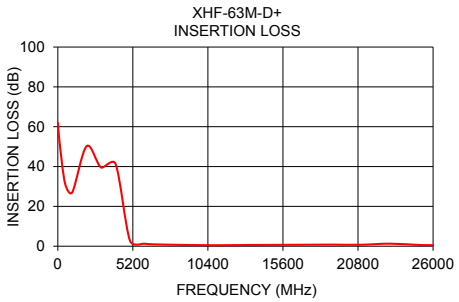
[2] Passband rating derates linearly to 0.5W at 105°C ambient
[3] Stopband rating derates linearly to0.63W at 105°C ambient
[4] Permanent damage may occur if any of these limits are exceeded.

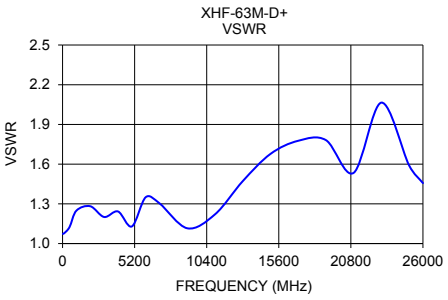
SPECIFICATION DEFINITION



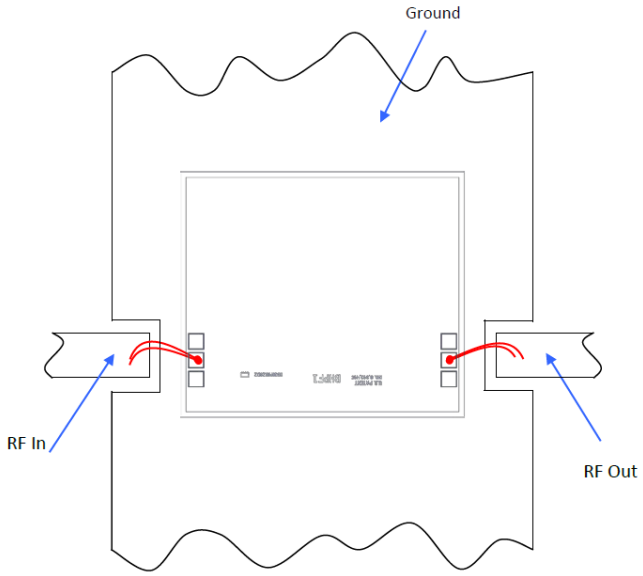
Typical Performance Data at 25°C

Frequency (MHz)	Insertion Loss (dB)	VSWR (:1)
10	61.97	1.07
100	53.58	1.08
500	31.53	1.12
1000	27.07	1.25
2000	50.27	1.28
3000	39.53	1.20
4000	41.35	1.24
5000	2.78	1.13
6000	1.27	1.35
7000	0.87	1.30
9000	0.63	1.12
11000	0.49	1.22
13000	0.61	1.47
15000	0.67	1.68
17000	0.74	1.78
19000	0.79	1.78
21000	0.73	1.53
23000	1.27	2.06
25000	0.63	1.59
26000	0.53	1.46





Assembly Diagram



Note: Ground bond wires are optional.

Assembly and Handling Procedure

1. Storage
   Dice should be stored in a dry nitrogen purged desiccators or equivalent.
2. ESD
   MMIC Gallium Arsenide (GaAs) filter dice are susceptible to electrostatic and mechanical damage. Die are supplied in antistatic protected material, which should be opened in clean room conditions at an appropriately grounded anti-static worksta tion. Devices need careful handling using correctly designed collets, vacuum pickup tips or sharp antistatic tweezers to deter ESD damage to dice.
3. Die Attach
   The Die mounting surface must be clean and flat. Using conductive silver filled epoxy, recommended epoxies are DieMat DM6030Hk-PT/H579/H579 or Ablestik 84-1LMISR4. Apply sufficient epoxy to meet required epoxy bond line thickness, epoxy fillet height and epoxy coverage around total Die periphery. Parts shall be cured in a nitrogen filled atmosphere per manufac turer's cure condition. It is recommended to use antistatic Die pick up tools only.
4. Wire Bonding
   Bond pad openings in the surface passivation above the bond pads are provided to allow wire bonding to the dice gold bond pads. Thermosonic bonding is used with minimized ultrasonic content. Bond force, time, ultrasonic power and temperature are all critical parameters. Suggested wire is pure gold, 1 mil diameter. Bonds must be made from the bond pads on the Die to the package or substrate. All bond wires should be kept as short as low as reasonable to minimize performance degradation due to undesirable series inductance.

Additional Detailed Technical Information

additional information is available on our dash board.

Performance Data	Data Table
	Swept Graphs
	S-Parameter (S2P Files) Data Set with and without port extension(.zip file)
Case Style	Die
Die Ordering and packaging information	Quantity, Package — Model No. Small, Gel - Pak: 5,10,50,100 KGD* — XHF-63M-DG+ Medium†, Partial wafer: KGD*<925 — XHF-63M-DP+ †*Available upon request contact sales representative* Refer to AN-60-067
Environmental Ratings	ENV-80

*Known Good Dice ("KGD") means that the dice are taken from PCM good wafer and visually inspected in question have been subjected to Mini-Circuits while this is not definitive, it does help to provide a higher degree of confidence that dice are capable of meeting typical RF electrical parameters specified by Mini-Circuits.

ESD Rating**

Human Body Model (HBM): Class 2 (Pass 2000V) in accordance with ANSI/ESD STM 5.1 - 2001

** Tested in industry standard MCLP 3x3 mm, 12-lead package.

Additional Notes

A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.

B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuit's applicable established test performance criteria and measurement instructions.

C. The parts covered by this specification document are subject to Mini-Circuits standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the Standard Terms and the exclusive rights and remeDies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/MCLStore/terms.jsp

D. Mini-Circuits does not warrant the accuracy or completeness of the information, text, graphics and other items contained within this document and same are provided as an accommodation and on an "As is" basis, with all faults.

E. Purchasers of this part are solely responsible for proper storing, handling, assembly and processing of Known Good Dice (including, without limitation, proper ESD preventative measures, Die preparation, Die attach, wire bond ing and related assembly and test activities), and Mini-Circuits assumes no responsibility therefor or for environmental effects on Known Good Dice.

F. Mini-Circuits and the Mini-Circuits logo are registered trademarks of Scientific Components Corporation d/b/a Mini-Circuits. All other third-party trademarks are the property of their respective owners. A reference to any third-party trademark does not constitute or imply any endorsement, affiliation, sponsorship, or recommendation by any such third-party of Mini-Circuits or its products.

MMIC Reflectionless High Pass Filter Die XHF-63M-D+

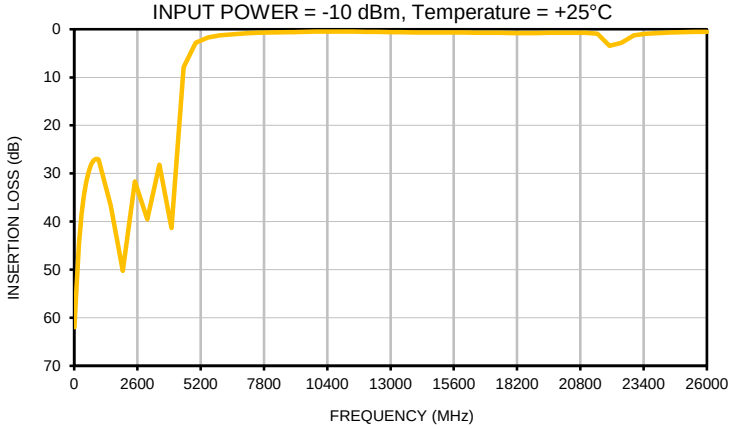
Typical Performance Data

Test Condition @ Temperature = +25°C

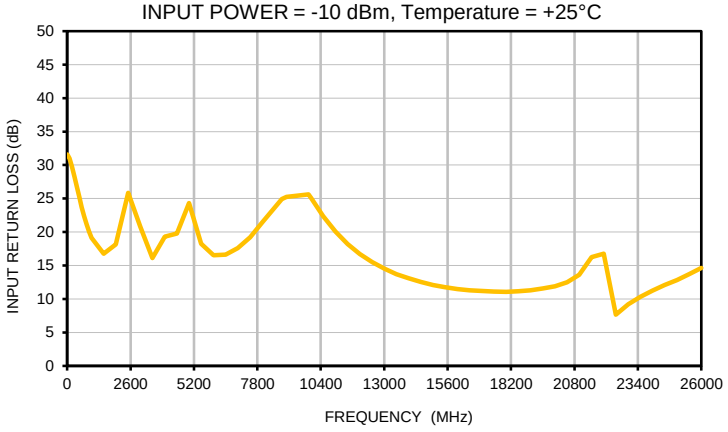
FREQ. (MHz)	INSERTION LOSS (dB)	INPUT RETURN LOSS (dB)	OUTPUT RETURN LOSS (dB)
10	61.97	31.58	28.94
100	53.58	31.00	28.66
200	44.51	29.76	27.97
300	38.56	28.24	26.98
400	34.45	26.70	25.87
500	31.53	25.16	24.68
600	29.47	23.72	23.49
700	28.07	22.38	22.33
800	27.24	21.15	21.24
900	26.91	20.07	20.25
1000	27.07	19.12	19.41
1500	36.65	16.74	17.32
2000	50.27	18.16	19.02
2500	31.66	25.87	27.64
3000	39.53	20.80	21.27
3500	28.16	16.09	16.78
4000	41.35	19.32	20.31
4500	7.92	19.80	20.37
5000	2.78	24.32	25.70
5500	1.69	18.26	18.37
6000	1.27	16.53	16.67
6500	1.03	16.64	16.84
7000	0.87	17.61	17.98
7500	0.76	19.24	19.88
8000	0.68	21.46	22.62
8800	0.64	24.92	28.05
9000	0.63	25.26	28.76
9900	0.51	25.63	27.34
10000	0.50	25.12	26.41
10500	0.48	22.39	22.70
11000	0.49	20.04	20.08
11500	0.51	18.22	18.16
12000	0.53	16.70	16.62
12500	0.57	15.53	15.42
13000	0.61	14.52	14.39
13500	0.64	13.69	13.54
14000	0.64	13.08	12.90
14500	0.65	12.54	12.38
15000	0.67	12.09	11.94
15500	0.68	11.74	11.59
16000	0.70	11.48	11.33
16500	0.71	11.30	11.17
17000	0.74	11.21	11.07
17500	0.76	11.12	10.99
18000	0.79	11.08	10.95
18500	0.81	11.14	10.98
19000	0.79	11.29	11.03
19500	0.75	11.57	11.27
20000	0.73	11.88	11.67
20500	0.71	12.49	12.35
21000	0.73	13.63	13.52
21500	0.96	16.26	16.34
22000	3.43	16.74	17.23
22500	2.80	7.66	7.72
23000	1.27	9.18	9.21
23500	0.94	10.32	10.33
24000	0.79	11.23	11.26
24500	0.69	12.06	12.12
25000	0.63	12.84	12.95
25500	0.57	13.68	13.89
26000	0.53	14.61	14.84

Typical Performance Curves

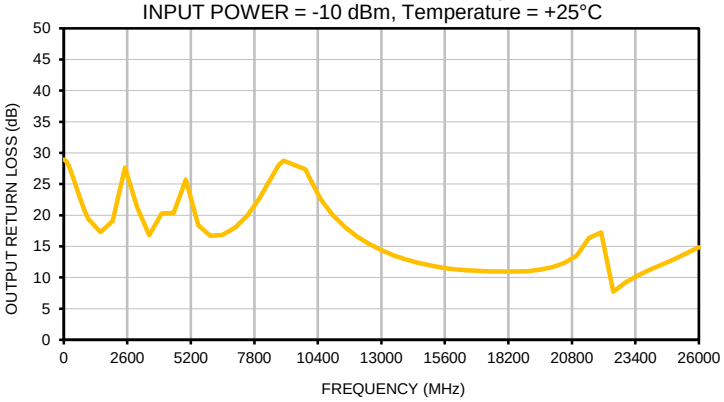
INSERTION LOSS vs. FREQUENCY
INPUT POWER = -10 dBm, Temperature = +25°C



INPUT RETURN LOSS vs. FREQUENCY
INPUT POWER = -10 dBm, Temperature = +25°C



OUTPUT RETURN LOSS vs. FREQUENCY
INPUT POWER = -10 dBm, Temperature = +25°C



Mini-Circuits

Environmental Specifications ENV80

All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-40° to 85° C or -40° to 105° C or -55° to 105° C or -45° to 105° C Ambient Environment	Refer to Individual Model Data Sheet
Storage Environment (Die)	-65° to 150°C	Individual Model Data Sheet
Storage Environment(Packaging)	-40° to 70°C and 40 to 60% humidity (In Factory Shipped Package)	

This document and its contents are the property of Mini-Circuits.